

AMENDMENT TO THE CLAIMS

Please amend the claims as follows:

Claims 1-16 (Canceled)

17. (Currently Amended) A process for treating a substrate comprising:

~~at least~~ forming an organic layer on said substrate[[,] ; and

reflowing said organic layer at a substrate temperature from 15 degrees to 40

degrees centigrade.

18. (Currently Amended) The process as set forth in claim 17, ~~in which~~ wherein a

deformed organic layer is formed from said organic layer in said reflowing, and said

deformed organic layer is thinner than said organic layer.

19. (Currently Amended) The process as set forth in claim 18, ~~in which~~ wherein said

deformed organic layer is equal in thickness to or less than a half ~~third~~ of the thickness of

said organic layer.

20. (Currently Amended) The process as set forth in claim 17, ~~in which~~ wherein a

chemical solution is penetrated into said organic layer so as to dissolve part of said

organic layer, thereby reflowing said organic layer.

21. (Currently Amended) The process as set forth in claim 17, ~~in which~~ wherein a chemical solution is penetrated into said organic layer so as dissolve part of said organic layer for the reflowing, and heat is applied to said organic layer so as to reflow part of said organic layer.

22. (Currently Amended) The process as set forth in claim 20, ~~in which~~ wherein said organic layer is exposed to a gaseous mixture of organic solution ~~containing at least comprising an~~ organic solvent for making said chemical solution penetrate into said organic layer.

23. (Currently Amended) The process as set forth in claim 21, ~~in which~~ wherein said organic layer is exposed to a high-temperature ambient at 50-300 degrees centigrade for applying the heat.

24. (Currently Amended) The process as set forth in claim 22, ~~in which~~ wherein a temperature of said gaseous mixture ranges from 15 degrees to 40 degrees centigrade.

25. (Currently Amended) The process as set forth in claim 20, ~~in which~~ wherein a deformed organic layer produced from said organic layer is thinner than said organic layer after the reflowing through the dissolution.

26. (Currently Amended) The process as set forth in claim 20, ~~in which~~ wherein said chemical solution or said organic solution including ~~containing~~ said organic solvent

KUW.029CONT
comprises an organic solution comprising an containing at least organic solvent selected from the group consisting of alcohols expressed by a general formula of R-OH, alkoxyalcohols, ethers expressed by a general formula of R-O-R, Ar-O-R and Ar-O-Ar, esters, ketones, glycols, alkylene glycols, and glycol ethers where R is an alkyl group or a substituted alkyl group and Ar comprises a phenyl is Phenyl group or an aromatic ring other than except said phenyl group.

27. (Currently Amended) The process as set forth in claim 17, in which wherein said organic layer comprises a resist layer.

28. (Currently Amended) The process as set forth in claim 18, in which wherein a chemical solution is penetrated into said organic layer so as to dissolve part of said organic layer, thereby reflowing said organic layer.

29. (Currently Amended) The process as set forth in claim 19, in which wherein a chemical solution is penetrated into said organic layer so as to dissolve part of said organic layer, thereby reflowing said organic layer.

30. (Currently Amended) The process as set forth in claim 18, in which wherein a chemical solution is penetrated into said organic layer so as to dissolve part of said organic layer for the reflowing, and heat is applied to said organic layer so as to reflow part of said organic layer.

31. (Currently Amended) The process as set forth in claim 19, ~~in which~~ wherein a chemical solution is penetrated into said organic layer so as to dissolve part of said organic layer for the reflowing, and heat is applied to said organic layer so as to reflow part of said organic layer.

32. (Currently Amended) The process as set forth in claim 21, ~~in which~~ wherein said organic layer is exposed to a gaseous mixture of organic solution comprising an ~~containing at least~~ organic solvent for making said chemical solution penetrate into said organic layer.

33. (Currently Amended) The process as set forth in claim 21, ~~in which~~ wherein a deformed organic layer produced from said organic layer is thinner than said organic layer after the reflowing through the dissolution.

34. (Currently Amended) The process as set forth in claim 22, ~~in which~~ wherein a deformed organic layer produced from said organic layer is thinner than said organic layer after the reflowing through the dissolution.

35. (Currently Amended) The process as set forth in claim 23, ~~in which~~ wherein a deformed organic layer produced from said organic layer is thinner than said organic layer after the reflowing through the dissolution.

36. (Currently Amended) The process as set forth in claim 24, ~~in which~~ wherein a deformed organic layer produced from said organic layer is thinner than said organic layer after the reflowing through the dissolution.

37. (Currently Amended) The process as set forth in claim 21, ~~in which~~ wherein said chemical solution or said organic solution including containing said organic solvent comprises an organic solution comprising an containing at least organic solvent selected from the group consisting of alcohols expressed by a general formula of R-OH, alkoxyalcohols, ethers expressed by a general formula of R-O-R, Ar-O-R and Ar-O-Ar, esters, ketones, glycols, alkylene glycols, and glycol ethers where R is an alkyl group or a substituted alkyl group and Ar comprises a phenyl is Phenyl group or an aromatic ring other than except said phenyl group.

38. (Currently Amended) The process as set forth in claim 22, ~~in which~~ wherein said chemical solution or said organic solution including containing said organic solvent comprises an organic solution comprising an containing at least organic solvent selected from the group consisting of alcohols expressed by a general formula of R-OH, alkoxyalcohols, ethers expressed by a general formula of R-O-R, Ar-O-R and Ar-O-Ar, esters, ketones, glycols, alkylene glycols, and glycol ethers where R is an alkyl group or a substituted alkyl group and Ar comprises a phenyl is Phenyl group or an aromatic ring other than except said phenyl group.

39. (Currently Amended) The process as set forth in claim 18, ~~in which~~ wherein said organic layer comprises a resist layer.

40. (Currently Amended) The process as set forth in claim 19, ~~in which~~ wherein said organic layer comprises a resist layer.

41. (Currently Amended) The process as set forth in claim 20, ~~in which~~ wherein said organic layer comprises a resist layer.

42. (Currently Amended) The process as set forth in claim 21, ~~in which~~ wherein said organic layer comprises a resist layer.

43. (Currently Amended) The process as set forth in claim 22, ~~in which~~ wherein said organic layer comprises a resist layer.

44. (Currently Amended) The process as set forth in claim 23, ~~in which~~ wherein said organic layer comprises a resist layer.

45. (Currently Amended) The process as set forth in claim 24, ~~in which~~ wherein said organic layer comprises a resist layer.

46. (Currently Amended) The process as set forth in claim 25, ~~in which~~ wherein said organic layer comprises a resist layer.

47. (Currently Amended) The process as set forth in claim 26, ~~in which~~ wherein said organic layer comprises a resist layer.